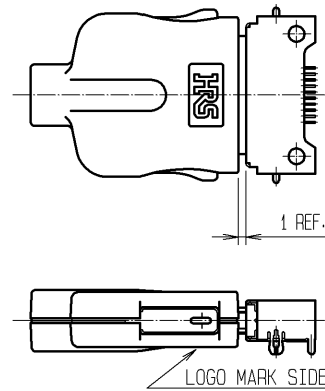
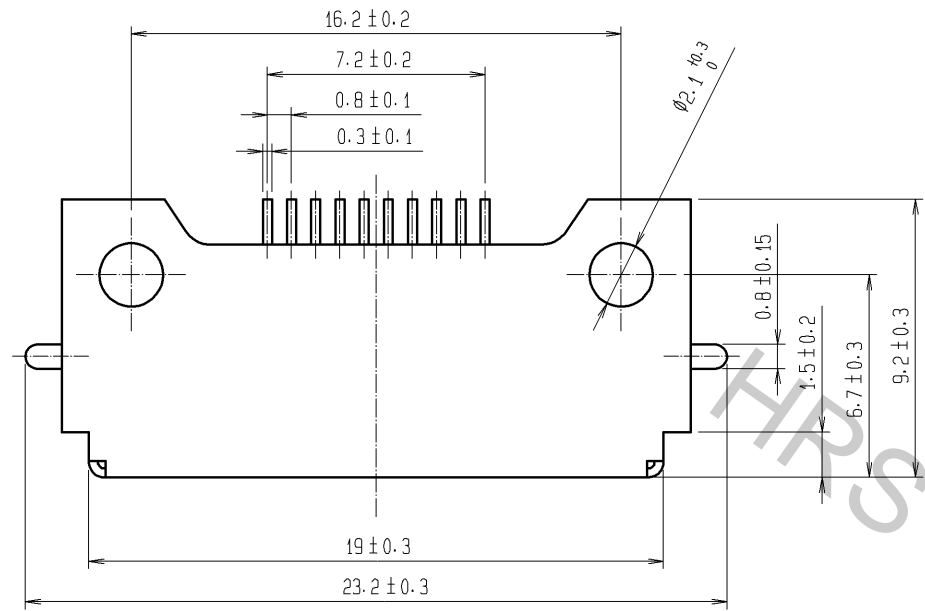
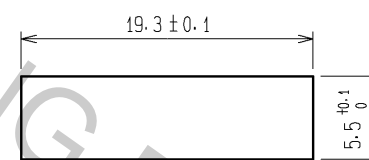


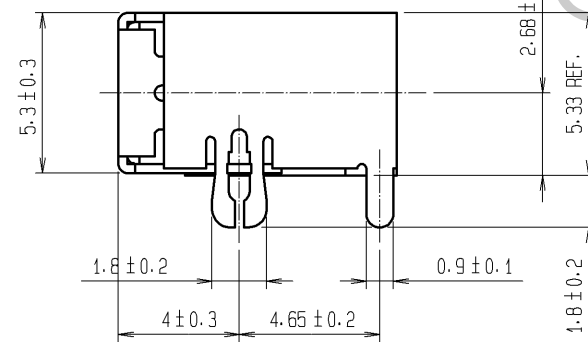
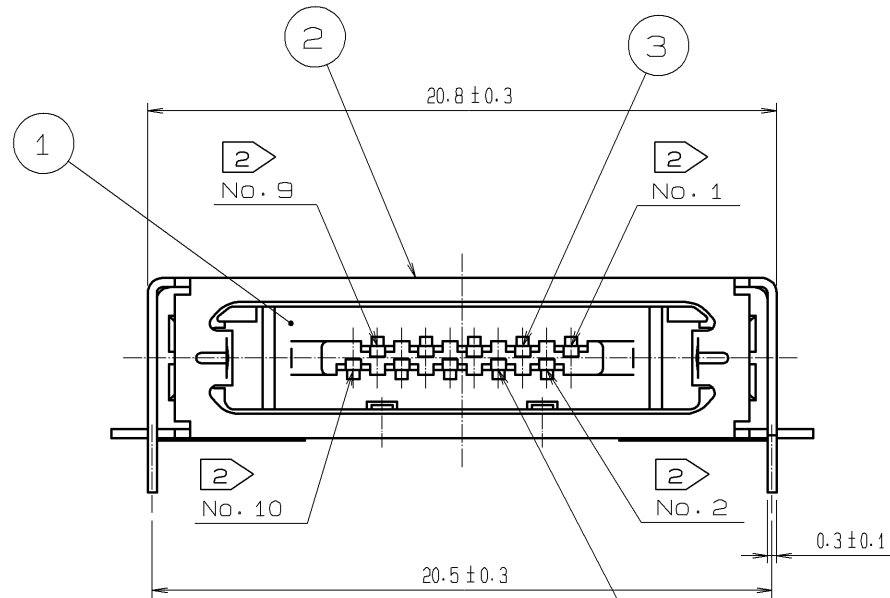
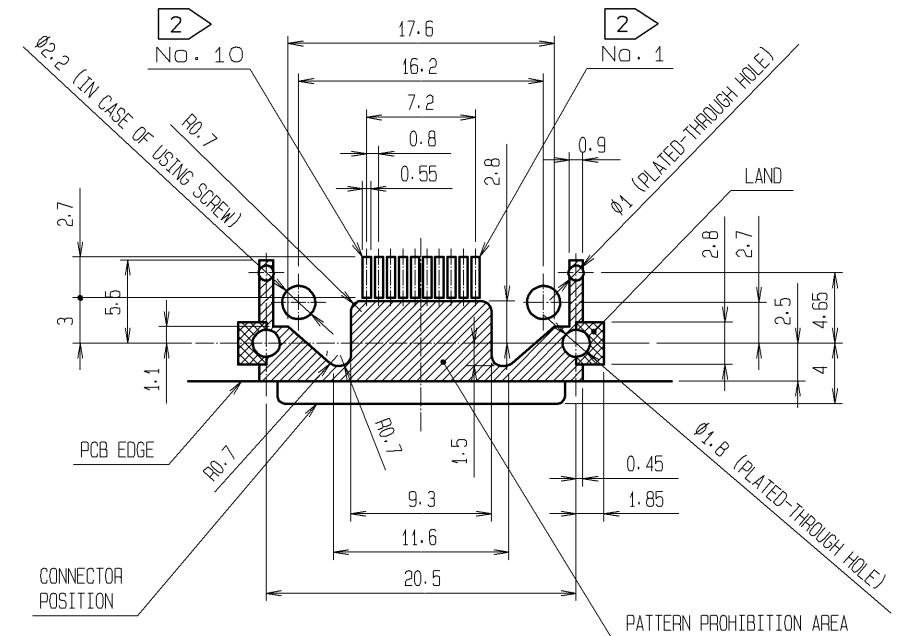
1 FIG-1 WITH MATED PLUG(1:1)



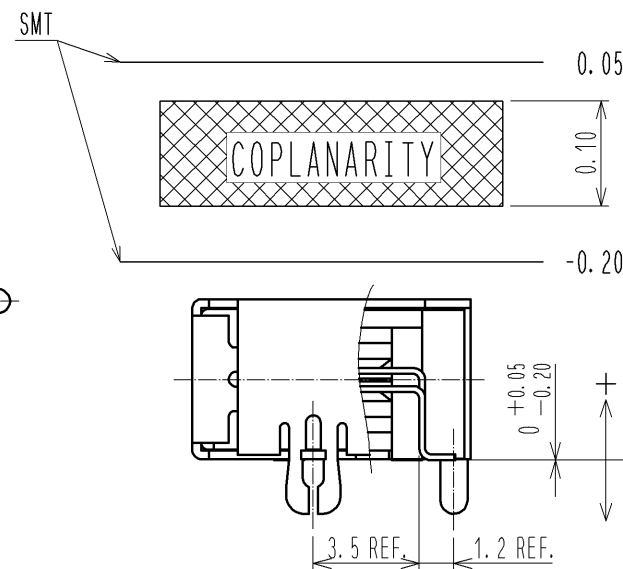
PANEL CUTOUT(2:1)
(PANEL THICKNESS t=1.5 mm MAX)



RECOMMENDED PC BOARD PATTERN
APPLICABLE PC BOARD t=0.8~1.6



4 FIG-2 SMT&COPLANARITY LEAD DIMENSIONS



- NOTES
- 1 LOCK MARK ON PLUG IN MATED CONDISION IS AS SHOWN FIG-1.
 - 2 CONTACT NO. IS AS SHOWN THE DRAWING.
 - 3 SMT LEAD DIMENSION FOR CONTACT (REF No. ③, ④) SHALL BE AS SHOWN IN THE FIG.2

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2μm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7μm MIN		4	COPPER ALLOY	CONTACT(SURFACE) : GOLD PLATING 0.2μm MIN CONTACT(INTERMEDIATE) : PALLADIUM NICKEL PLATING 0.7μm MIN	
2	STAINLESS STEEL	LEAD OVER : TIN REFLOW PLATING 1μm MIN LEAD UNDER : NICKEL PLATING 0.2μm MIN		1	POLYAMIDE	LEAD OVER : TIN COPPER PLATING 3μm MIN LEAD UNDER : NICKEL PLATING 2μm MIN	
1	POLYAMIDE	BLACK, UL94V-0					

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	4:1	5	DIS-E-003883	MT. ITANO	YH. ENAMI	11.08.12

APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
HO. MIWA	YH. ENAMI	TU. TANIGUCHI	TU. TANIGUCHI	EDC3-120710-01	3560-10SR(50)	CL235-0008-2-50